Search Notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	332	(438/430).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 16:54
L2	1556	(438/424).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 16:54
L3	332	(438/430).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 16:54
L4	18	L3 and rie and polysilicon and ((thermal adj oxide) or (lpteos))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
L5	18	L3 and rie and polysilicon and ((thermal adj oxide) or (lpteos))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
L6	88	trench and rie and polysilicon and ((thermal adj oxide) or (lpteos)) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
L7	1	trench and rie and polysilicon and (lpteos) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
L8	71	trench and rie and polysilicon and (ozone with teos) and lpcvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55
L9	36	trench and rie and polysilicon and (ozone with teos) and hdp with cvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55

L10	14	trench and rie and polysilicon and lpteos	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55
L11	79	psg same usg and trench and sti and sidewall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55
L12	0	"LEE-JAE.in. "	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 17:00
L13	0	"LEE-JAE.in. "	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 17:01
L14	4	lee-jae.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 17:01
S1	1462	(438/424).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 16:54
S2	324	(438/430).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 16:54
S3	1	S2 and rie and polysilicon and ((thermal adj oxide) or (lpteos)) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:22
S4	18	S2 and rie and polysilicon and ((thermal adj oxide) or (lpteos))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
S5	1218	trench and rie and polysilicon and ((thermal adj oxide) or (lpteos))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:13

S6	81	trench and rie and polysilicon and ((thermal adj oxide) or (lpteos)) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
S7	1	trench and rie and polysilicon and (lpteos) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:54
S8	1	trench and rie and polysilicon and (lp-teos) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:14
S9	1	trench and rie and polysilicon and (lpteos) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:23
S10	80	trench and rie and polysilicon and (thermal adj oxide) and hdp with cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:23
S11	80	trench and rie and polysilicon and (thermal adj oxide) and hdp with cvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:23
S12	123	trench and rie and polysilicon and (teos) and hdp with cvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 20:23
S13	33	trench and rie and polysilicon and (ozone with teos) and hdp with cvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55
S14	66	trench and rie and polysilicon and (ozone with teos) and lpcvd and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55
S15	14	trench and rie and polysilicon and lpteos	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55

S16	112	psg and usg and trench and sti	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 10:14
S17	78	psg and usg and trench and sti and sidewall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 10:14
S18	66	psg same usg and trench and sti and sidewall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:55